

H262-Z66

High Density Server - DP 2U 4 Nodes Server



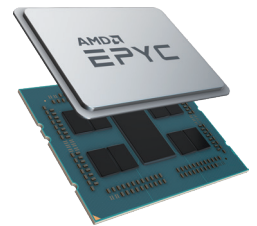
Features

- 2U - 4 nodes rear access server system
- Dual AMD EPYC™ 7002 series processor family
- 8-Channel RDIMM/LRDIMM DDR4 per processor, 64 x DIMMs
- 8 x 1Gb/s LAN ports (Intel® I350-AM2)
- 4 x Dedicated management ports
- 1 x CMC global management port
- 12 x 2.5" NVMe hot-swappable SSD bays
- 12 x 2.5" SATA/SAS hot-swappable HDD/SSD bays
- 8 x M.2 with PCIe Gen3 x4 interface
- 8 x Low profile PCIe Gen4 x16 expansion slots
- 4 x OCP 2.0 Gen3 x16 mezzanine slots
- Aspeed® AST2500 remote management controller
- 2+0 2200W 80 PLUS Platinum power supply

AMD EPYC™ 7002 Series Processor (Rome)

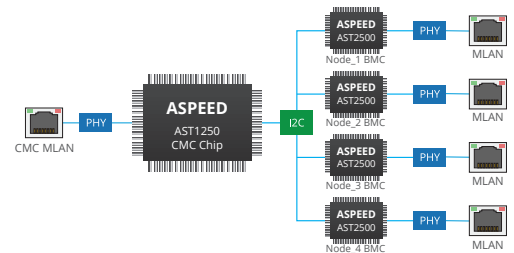
The next generation of AMD EPYC has arrived, providing incredible compute, IO and bandwidth capability – designed to meet the huge demand for more compute in big data analytics, HPC and cloud computing.

- ✓ Built on **7nm** advanced process technology, allowing for denser compute capabilities with lower power consumption
- ✓ Up to **64 core** per CPU, built using Zen 2 high performance cores and AMD's innovative chiplet architecture
- ✓ Supporting **PCIe Gen 4.0** with a bandwidth of up to 64GB/s, twice of PCIe Gen 3.0
- ✓ **Embedded security protection** to help defend your CPU, applications, and data



CMC for Chassis Management & Multi-Node Monitoring

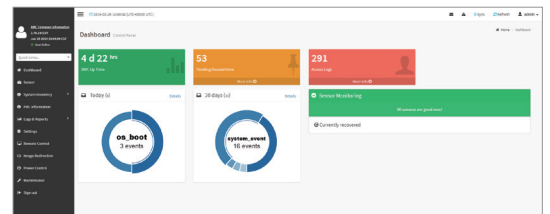
GIGABYTE's H-Series Servers feature an Aspeed CMC (Central Management Controller) for chassis-level management and node-level monitoring (by connecting internally to Aspeed BMCs integrated on each node). This results only in one MLAN connection required to perform monitoring of all four nodes*, resulting in less ToR (Top of Rack) cabling and switch connections.



GIGABYTE Management Console (AMI MegaRAC SP-X)

This GIGABYTE server product utilizes a AMI MegaRAC SP-X platform for BMC server management, with a feature rich and easy to use browser-based graphical user interface. Notable features include:

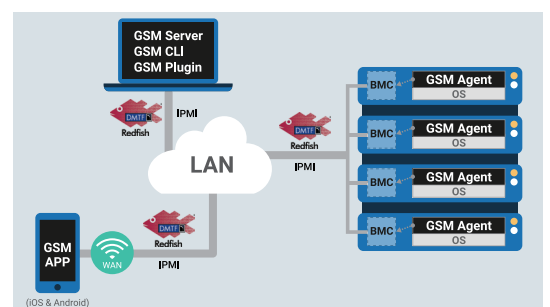
- **RESTful API support** (including the latest DMTF standards of Redfish) allows the administrator to integrate with 3rd party applications for server management
- **HTML5-based iKVM** remote management client included as a standard feature, no additional add-on license required to purchase
- **Detailed FRU information** from SMBIOS
- **Pre-event automatic video recording** feature from 10 to 30 seconds
- **SAS / RAID controller monitoring** feature



GIGABYTE Server Management (GSM)

GIGABYTE Server Management (GSM) is GIGABYTE's proprietary multiple server remote management software platform, available as a free download from each GIGABYTE server product page. GSM is compatible with either IPMI or Redfish (RESTful API) connection interfaces, and comprises the following sub-programs:

- **GSM Server** • **GSM CLI** • **GSM Agent** • **GSM Mobile** • **GSM Plugin**



Specification

Dimensions (WxHxD)	2U 4 Nodes - Rear access 440 x 87.5 x 840 mm	Power Supply	2+0 2200W 80 PLUS Platinum power supply AC Input: - 100-127V~/ 14A, 47-63Hz - 200-240V~/ 12.6A, 47-63Hz DC Output: - Max 1200W/ 100-127V~ +12.12V/ 95.6A +12Vsb/ 3.5A - Max 2200W/ 200-240V +12.12V/ 178.1A +12Vsb/ 3.5A System power supply requires C19 type power cord
Motherboard	MZ62-HD0	System Management	Aspeed® AST2500 management controller GIGABYTE Management Console (AMI MegaRAC SP-X) Dashboard JAVA Based Serial Over LAN HTML5 KVM Sensor Monitor (Voltage, RPM, Temperature, CPU Status ...etc.) Sensor Reading History Data FRU Information SEL Log in Linear Storage / Circular Storage Policy Hardware Inventory Fan Profile System Firewall Power Consumption Power Control LDAP / AD / RADIUS Support Backup & Restore Configuration Remote BIOS/BMC/CPLD Update Event Log Filter User Management Media Redirection Settings PAM Order Settings SSL Settings SMTP Settings
CPU	AMD EPYC™ 7002 series processor family Dual processors, 7nm technology Up to 64-core, 128 threads per processor TDP up to 200W NOTE: 1) If only 1 CPU is installed, some PCIe or memory functions might be unavailable 2) Contact GIGABYTE sales rep or technical support for more details about supporting cTDP 240W CPU Compatible with AMD EPYC™ 7001 series processor family	OS Compatibility	Windows Server 2016 (X2APIC/256T not supported) Windows Server 2019 Red Hat Enterprise Linux 7.6 (x64) or later Red Hat Enterprise Linux 8.0 (x64) or later SUSE Linux Enterprise Server 12 SP4 (x64) or later SUSE Linux Enterprise Server 15 SP1 (x64) or later Ubuntu 16.04.6 LTS (x64) or later Ubuntu 18.04.3 LTS (x64) or later VMware ESXi 6.5 EP15 or later VMware ESXi 6.7 Update3 or later Citrix Hypervisor 8.1.0
Socket	Per node: 2 x LGA 4094 Total: 8 x LGA 4094 Socket SP3	Weight	Net Weight: 28 kg Gross Weight: 50 kg
Chipset	System on Chip	System Fans	8 x 80x80x38mm (16,300rpm)
Memory	Per node: 16 x DIMM slots Total: 64 x DIMM slots DDR4 memory supported only 8-Channel memory architecture RDIMM modules up to 64GB supported LRDIMM modules up to 128GB supported Memory speed: Up to 3200 MHz	Operating	Operating temperature: 10°C to 35°C Operating humidity: 8%-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
LAN	Per node: 2 x 1GbE LAN ports (Intel® I350-AM2) 1 x Dedicated management port Total: 8 x 1GbE LAN ports (Intel® I350-AM2) 4 x Dedicated management ports 1 x 10/100/1000 *CMC global management port *CMC: Chassis Management Controller, to monitor all status of computing nodes	Packaging Dimensions	1180 x 779 x 300 mm
Video	Integrated in Aspeed® AST2500 2D Video Graphic Adapter with PCIe bus interface 1920x1200@60Hz 32bpp, DDR4 SDRAM Management chip on CMC board: Integrated in Aspeed® AST2520A2-GP	Packaging Content	1 x H262-Z66 8 x CPU heatsinks 1 x Rail Kit
Storage	Per node: 3 x 2.5" NVMe hot-swappable SSD bays 3 x 2.5" SATA/SAS hot-swappable HDD/SSD bays Total: 12 x 2.5" NVMe hot-swappable SSD bays 12 x 2.5" SATA/SAS hot-swappable HDD/SSD bays All storage bays are compatible with SATA devices	Part Numbers	Barebone package: 6NH262Z66MR-00 - Motherboard: 9MZ62HD0NR-00 - Rail kit: 25HB2-AN6103-K0R - CPU heatsink: 25ST1-44320H-A0R/25ST1-44320I-A0R - Back plane board: 5CFPH004NR-00 - NVMe M.2 extension card for Slot_R: 9CMTPO4RNR-00 (optional extra) - Power Supply: 25EPO-222003-D0S - C19 type power cord 125V/15A (US): 25CP1-018000-Q0R (optional extra) - C19 type power cord 250V/16A (EU): 25CP3-01830H-Q0R (optional extra) - C19 type power cord 250V/15A (US): 25CP1-018300-Q0R (optional extra) - Ring topology kit: 6NH262Z65SR-00-100 (optional extra)
Expansion Slots	Per node: 2 x Half-length low-profile slot with PCIe x16 (Gen4 x16) 1 x OCP mezzanine slot with PCIe Gen3 x16 bandwidth 2 x M.2 slots Total: 8 x Low profile half-length slots with PCIe x16 (Gen4 x16) 4 x OCP 2.0 mezzanine slots with PCIe Gen3 x16 bandwidth 8 x M.2 slots - M-key, PCIe Gen3 x4 - Supports NGFF-2242/2260/2280/22110 cards - CPU TDP is limited to 155W if using M.2 device	Internal I/O	Per node: 2 x M.2 slots, 1 x COM header, 1 x TPM header, 1 x BMC SGPIO header, 1 x JTAG BMC header, 1 x PLD header, 1 x Clear CMOS jumper, 1 x IPMB connector
Internal I/O	Per node: 2 x M.2 slots, 1 x COM header, 1 x TPM header, 1 x BMC SGPIO header, 1 x JTAG BMC header, 1 x PLD header, 1 x Clear CMOS jumper, 1 x IPMB connector	Front I/O	Per node: 1 x Power button with LED, 1 x ID button with LED, 1 x Status LED Total: 4 x Power button with LED, 4 x ID button with LED, 4 x Status LED, 1 x CMC status LED
Front I/O	Per node: 1 x Power button with LED, 1 x ID button with LED, 1 x Status LED Total: 4 x Power button with LED, 4 x ID button with LED, 4 x Status LED, 1 x CMC status LED	Rear I/O	Per node: 2 x USB 3.0, 1 x VGA, 2 x RJ45, 1 x RJ45 MLAN, Total: 8 x USB 3.0, 4 x VGA, 8 x RJ45, 4 x RJ45 MLAN, 1 x CMC global management port
Rear I/O	Per node: 2 x USB 3.0, 1 x VGA, 2 x RJ45, 1 x RJ45 MLAN, Total: 8 x USB 3.0, 4 x VGA, 8 x RJ45, 4 x RJ45 MLAN, 1 x CMC global management port	Backplane I/O	24 x ports Speed and bandwidth: SATA 6Gb/s or SAS 12Gb/s or PCIe Gen3 x4 per port
Backplane I/O	24 x ports Speed and bandwidth: SATA 6Gb/s or SAS 12Gb/s or PCIe Gen3 x4 per port	TPM	1 x TPM header with SPI interface Optional TPM2.0 kit: CTM010

* All specifications are subject to change without notice. Please visit our website for the latest information.

* AMD, and the AMD Arrow logo, AMD EPYC, AMD Radeon Instinct and combinations thereof are trademarks of Advanced Micro Devices, Inc.

